

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of
SHAO-CHUNG HU; TENG-CHUN
TSAI; CHIA-LIN HSU; AND YUNG-
TSUNG WEI

Group Art Unit: N / A

Examiner: N / A

Serial No.: N/A

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT ACCOMPANYING NEW APPLICATION TRANSMITTAL

Dear Sir:

In connection to the enclosed new Divisional Patent Application, the specification of which is attached hereto, kindly amend said application as follows:

IN THE SPECIFICATION

Please add Continuation-In-Part of Copending Application Number 09/854,006 in the first line of the specification.